

PICO-APL3

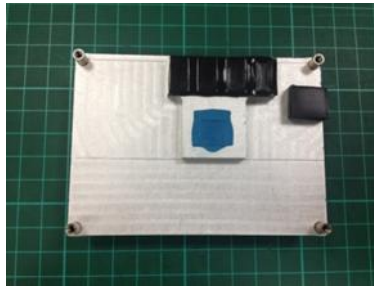
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: 1. There are eight temperature points marginal passed. 2. There are four components that lack the Tc or Tj specifications, So we are unable to determine.															
Test Result Summary																
	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 20%;"></th> <th style="width: 20%;">Critical</th> <th style="width: 20%;">Major</th> <th style="width: 20%;">Minor</th> <th style="width: 20%;">Enhancement</th> </tr> </thead> <tbody> <tr> <td>Defect Found</td> <td style="text-align: center;">0</td> <td style="text-align: center;">0</td> <td style="text-align: center;">0</td> <td style="text-align: center;">12</td> </tr> <tr> <td>Defect Unsolved</td> <td style="text-align: center;">0</td> <td style="text-align: center;">0</td> <td style="text-align: center;">0</td> <td style="text-align: center;">12</td> </tr> </tbody> </table>		Critical	Major	Minor	Enhancement	Defect Found	0	0	0	12	Defect Unsolved	0	0	0	12
	Critical	Major	Minor	Enhancement												
Defect Found	0	0	0	12												
Defect Unsolved	0	0	0	12												

Issue date	QE Manager	Test Engineer
2017 / 09 / 29	KJ Wang	Jerry Chen

Sample Configuration & Quantity Under Test

- **Model name : PICO-APL3**
- **M/B Name : PICO-APL3 / Rev. A0.2**
- **CPU : Intel Pentium N4200 / 1.10 GHz**
- **BIOS : PICO-APL3 R0.4 (ZAP3AM04) (08/21/2017)**
- **Chipset: Intel Apollo Lake**
- **Memory : On board / DDR3L 4GB / SEC K4B8G1646D MYKO**
- **2.5" SATA HDD: TOSHIBA 160GB / MK1655GSX**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro**
- **Adapter: FSP / FSP060-DIBAN2 / 12V 5A**
- **AT Power Supply: Zippy EMACS HG2-6400P (For 2.5" SATA HDD)**
- **Heat Sink:**

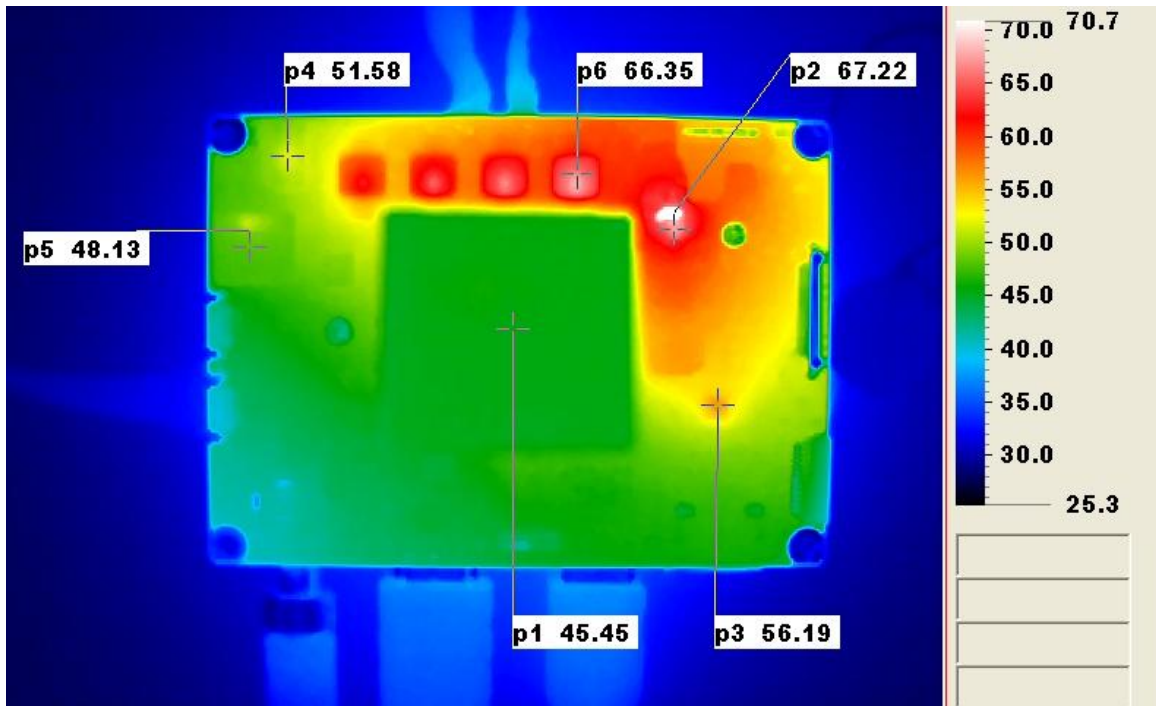


Thermal Image Analysis

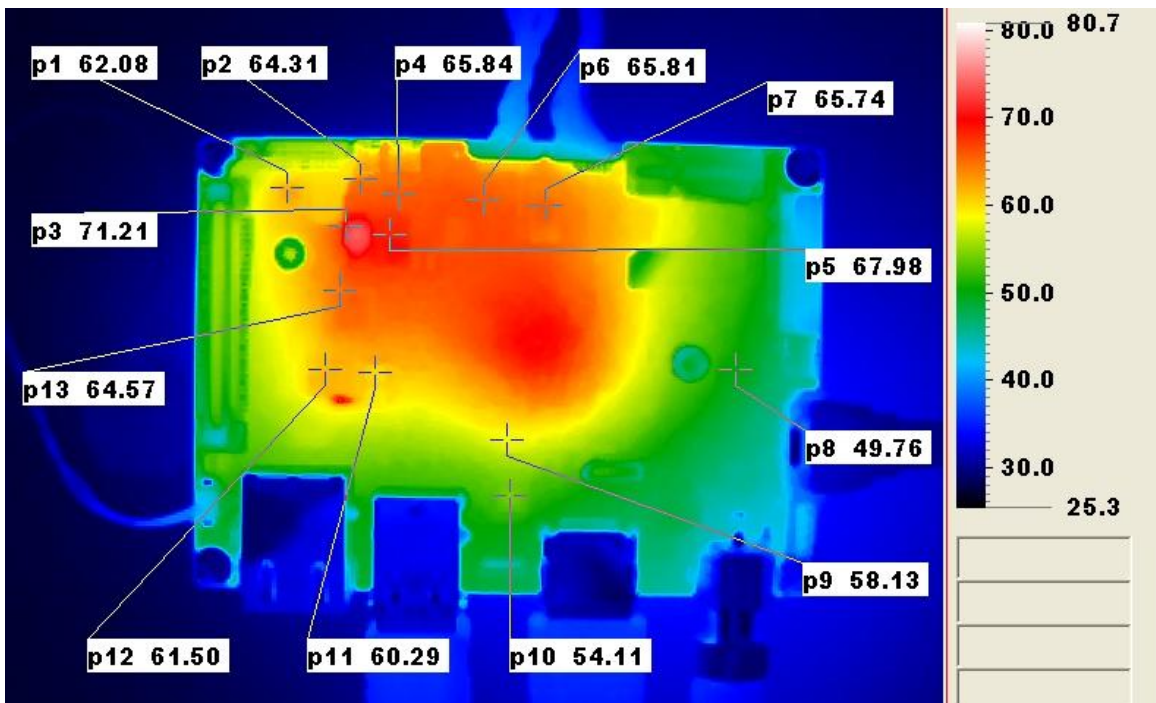
1. Test Date: 2017-09-28
2. Test Product: PICO-APL3
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
Date of Calibration: 09/08/2017
Due date of Calibration: 09/07/2018
Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
Date of Calibration: 11/29/2016
Due date of Calibration: 11/28/2017
Serial Number: 1051444
5. Test Condition:
Test by DA-100: 25.0°C with Heat Sink
6. Take Picture Time:
After power on 2 hours

Temperature Profile Test:

Front Side:



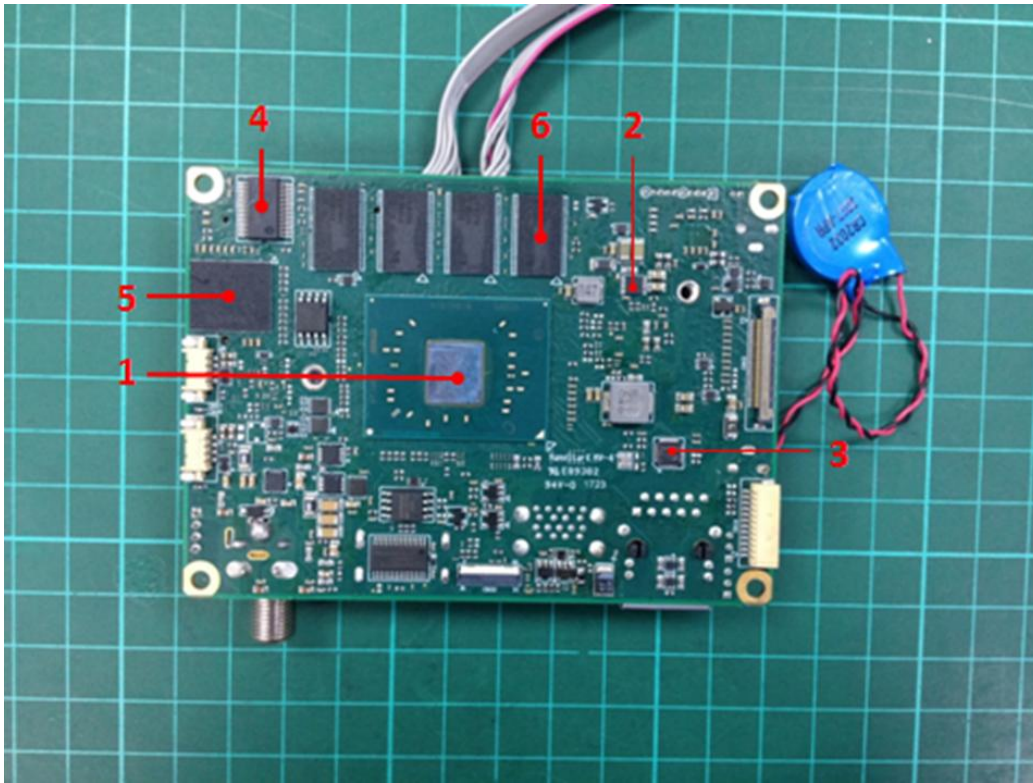
Rear Side:



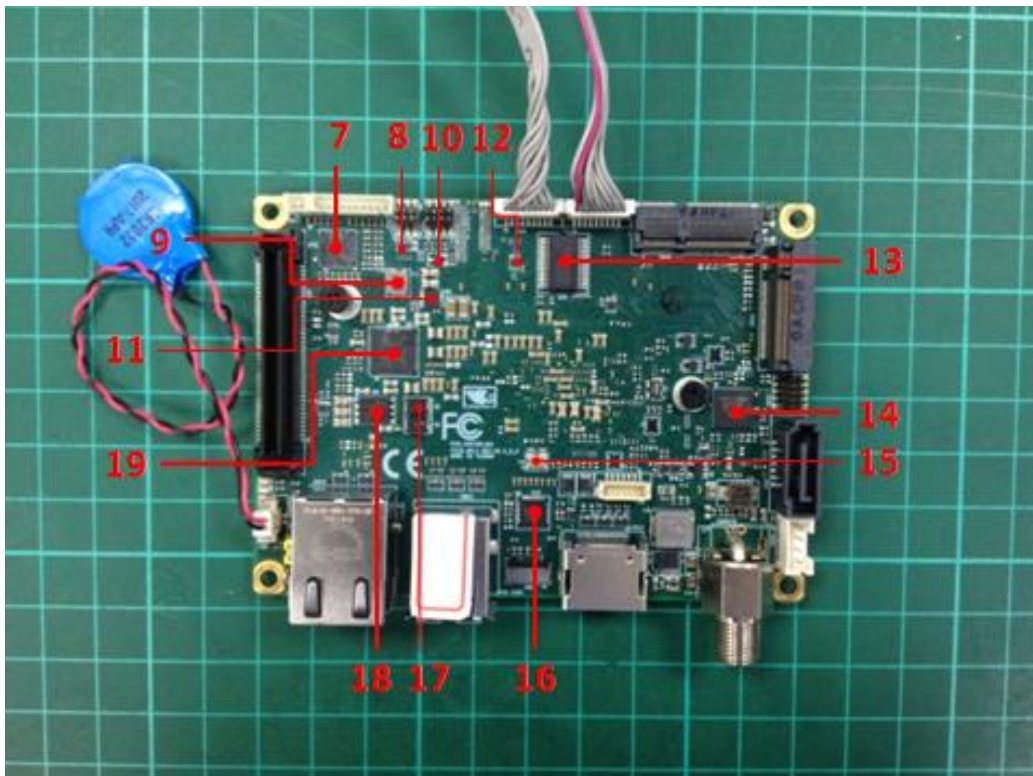
Terminal Recorder:

Measuring Thermal Couple Position :

Front Side:



Rear Side:



Using YOKOGAWA Inc / DA100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2) TPT(*3)		Note
				25°C	60°C	
1	U25	Intel Pentium N4200 / 1.10 GHz	105	55.7	90.7	
2	Q17	PMPAK3X3 DUAL N-MOSFET..FAIRCHILD.FDMC7200S	125	71.7	106.7	
3	U80	Gigabit Ethernet Chip.QFN 32P.SMD.REALTEK.RTL8111G-CG	100	63.6	98.6	Note 6
4	U99	S232 Driver/Receiver.15KV ESD.SSOP TI.TRS213IDBR	125	54.8	89.8	
5	U38	eMMC Flash.32GB.3.3V..Kingston.EMMC32G-M525-A51	85	52.9	87.9	Note 6
6	U36	DDR3L.512M.Dual-Die.1600MHz. Samsung.K4B8G1646D-MYK0	95	56.8	91.8	Note 6
7	U78	HDA Audio Codec.w/Class-D AMP.REALTEK.ALC269Q-VC2-GR	100	63.7	98.7	Note 6
8	U89	ESDDiode.AIR 15KV.SLP2510P8.LITE-ON.L05ESDL5V0NA-4	100	62.8	97.8	Note 6
9	L1	Coil.0.47uH.DCR=14mΩ.Irms=7Amp.GOTREND.GSTD4020PE-R47	N/A	71.9	106.9	Note 6
10	D1	D Schottky.Vr=40V.If=0.2A.Ir=0.2uA.WILLAS.BAS40W-06	100	60.6	95.6	Note 6
11	Q5	DUAL N-MOSFET.Vgs1/2=(+/-)20V.FAIRCHILD.FDMC7200S	125	65	100	
12	Q68	Dual N-Channel MOSFET.EMT6.SMD.ROHM.EM6K1GT2R	125	57.1	92.1	
13	U20	S232 Driver/Receiver.15KV ESD.SSOP TI.TRS213IDBR	125	57.7	92.7	
14	U5	Embedded Controller.SMD.ITE.IT8528VG/FX	85	51.6	86.6	Note 6
15	Y4	XTAL.19.200MHz.20PF.ARG0.AGX-19.200M-20-S3225-E-Z-TR	N/A	54.9	89.9	Note 6
16	U32	HDMI/DVI Level Shifter.HVQFN.NXP.PTN3366BSMP	N/A	54.9	89.9	Note 6
17	TC3	KO-CAP.330uF.2.5V.20%.KEMET.T520B337M2R5ATE015	N/A	60.7	95.7	Note 6
18	Q3	DualN-MOSFET.FAIRCHILD.FDMS3660S	125	63.1	98.1	
19	U8	PMIC.Intel Apollo Lake.DDR=1.35V.TI.TPS650942A0RSKR	100	64.2	99.2	Note 6
20	Air	Air Temperature	N/A	25	60	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "T_{AT}" indicates the actual measured temperature under 25°C working environmental.
3. "T_{PT}" indicates the predicted temperature under product specification.
4. **Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.
5. **RTC battery avoid to put on heat position.** Please do not exceed battery temperature specification.
6. Defect NO. : [E170401LABD03](#)